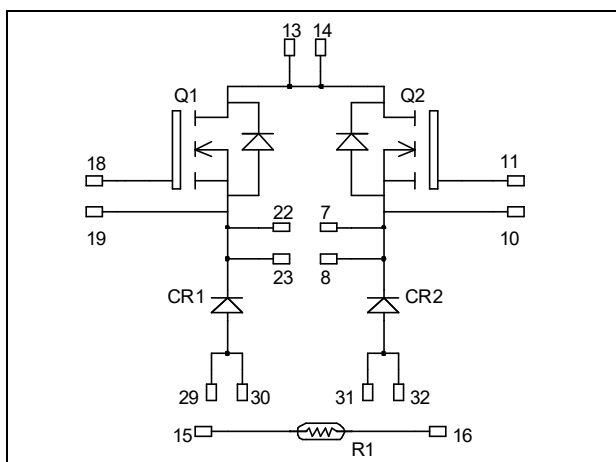


Dual Buck chopper MOSFET Power Module

$V_{DSS} = 1000V$

$R_{DSon} = 350m\Omega$ typ @ $T_j = 25^\circ C$

$I_D = 22A$ @ $T_c = 25^\circ C$



Application

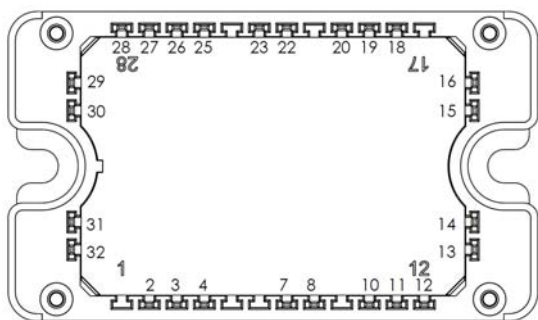
- AC and DC motor control
- Switched Mode Power Supplies

Features

- **Power MOS 7[®] MOSFETs**
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
- Internal thermistor for temperature monitoring

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- Each leg can be easily paralleled to achieve a single buck of twice the current capability
- RoHS Compliant



All multiple inputs and outputs must be shorted together
Example: 13/14 ; 29/30 ; 22/23 ...

All ratings @ $T_j = 25^\circ C$ unless otherwise specified

Absolute maximum ratings (per MOSFET)

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Voltage	1000	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	22
		$T_c = 80^\circ C$	17
I_{DM}	Pulsed Drain current	88	
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	420	$m\Omega$
P_D	Power Dissipation	$T_c = 25^\circ C$	390
I_{AR}	Avalanche current (repetitive and non repetitive)	25	A
E_{AR}	Repetitive Avalanche Energy	50	mJ
E_{AS}	Single Pulse Avalanche Energy	3000	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Electrical Characteristics (per MOSFET)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 1000V$			100	μA
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 11A$		350	420	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.5mA$	3		5	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			± 150	nA

Dynamic Characteristics (per MOSFET)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$		5.2		nF
C_{oss}	Output Capacitance	$V_{DS} = 25V$		0.88		
C_{rss}	Reverse Transfer Capacitance	$f = 1MHz$		0.16		
Q_g	Total gate Charge	$V_{GS} = 10V$		186		nC
Q_{gs}	Gate – Source Charge	$V_{Bus} = 500V$		24		
Q_{gd}	Gate – Drain Charge	$I_D = 22A$		122		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C $V_{GS} = 15V$ $V_{Bus} = 670V$ $I_D = 22A$ $R_G = 5\Omega$		18		ns
T_r	Rise Time			12		
$T_{d(off)}$	Turn-off Delay Time			155		
T_f	Fall Time			40		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C $V_{GS} = 15V, V_{Bus} = 670V$ $I_D = 22A, R_G = 5\Omega$		900		μJ
E_{off}	Turn-off Switching Energy			623		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 15V, V_{Bus} = 670V$ $I_D = 22A, R_G = 5\Omega$		1423		μJ
E_{off}	Turn-off Switching Energy			779		
R_{thJC}	Junction to Case Thermal Resistance				0.32	$^{\circ}C/W$

Chopper Diode ratings and characteristics (per diode)

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V _{RRM}	Peak Repetitive Reverse Voltage					1000	V
I _{RM}	Reverse Leakage Current	V _R =1000V				250	μA
I _F	DC Forward Current		T _c = 70°C		30		A
V _F	Diode Forward Voltage	I _F = 30A			1.9	2.3	V
		I _F = 60A			2.2		
		I _F = 30A	T _j = 125°C		1.7		
t _{rr}	Reverse Recovery Time	I _F = 30A V _R = 667V di/dt=200A/μs	T _j = 25°C		290		ns
	T _j = 125°C			390			
Q _{rr}	Reverse Recovery Charge			T _j = 25°C		670	
			T _j = 125°C		2350		
R _{thJC}	Junction to Case Thermal Resistance					1.2	°C/W

Thermal and package characteristics

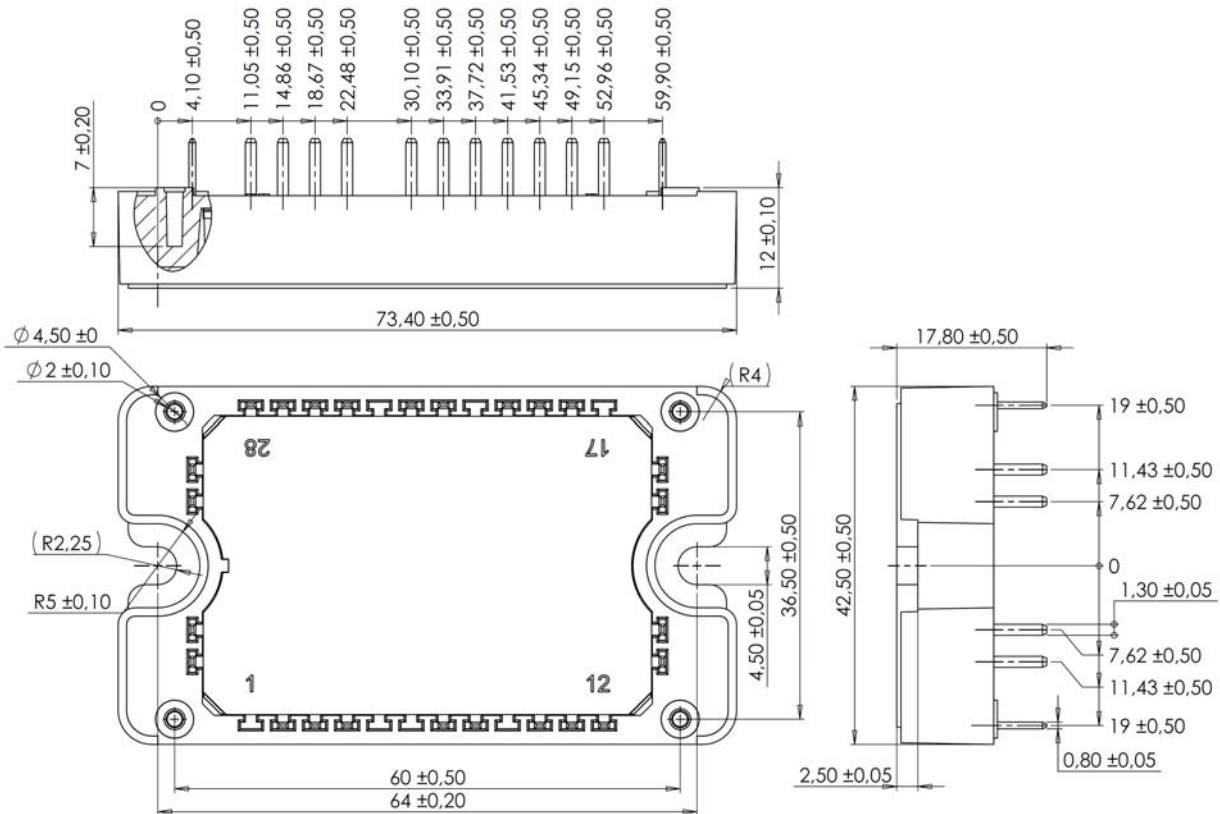
Symbol	Characteristic	Min	Max	Unit
V _{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz	4000		V
T _J	Operating junction temperature range	-40	150	°C
T _{JOP}	Recommended junction temperature under switching conditions	-40	T _{Jmax} - 25	
T _{STG}	Storage Temperature Range	-40	125	
T _C	Operating Case Temperature	-40	125	
Torque	Mounting torque	To heatsink	M4	N.m
Wt	Package Weight		110	g

Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C		50		kΩ
ΔR ₂₅ /R ₂₅			5		%
B _{25/85}	T ₂₅ = 298.15 K		3952		K
ΔB/B	T _C =100°C		4		%

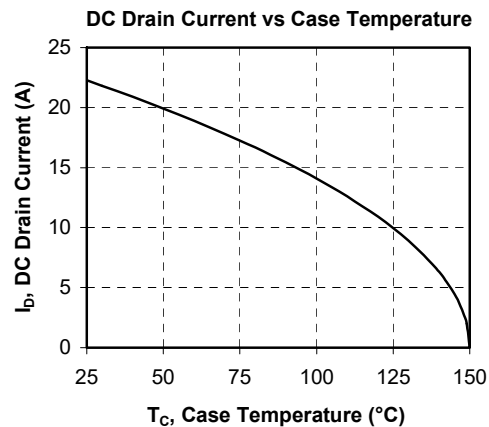
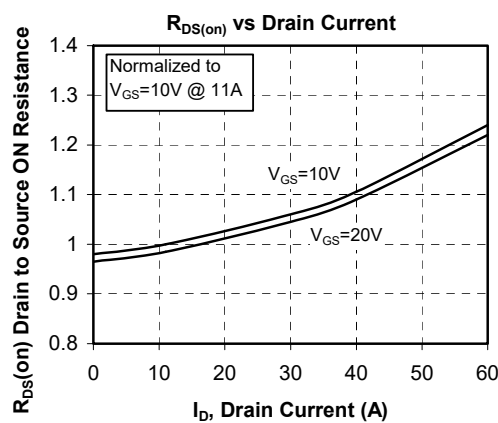
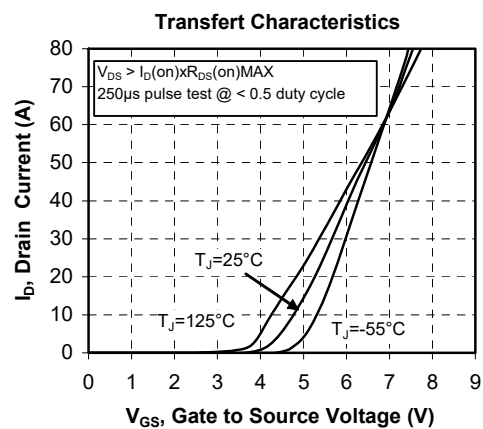
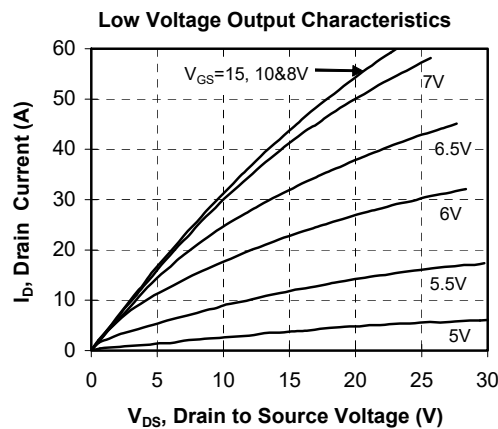
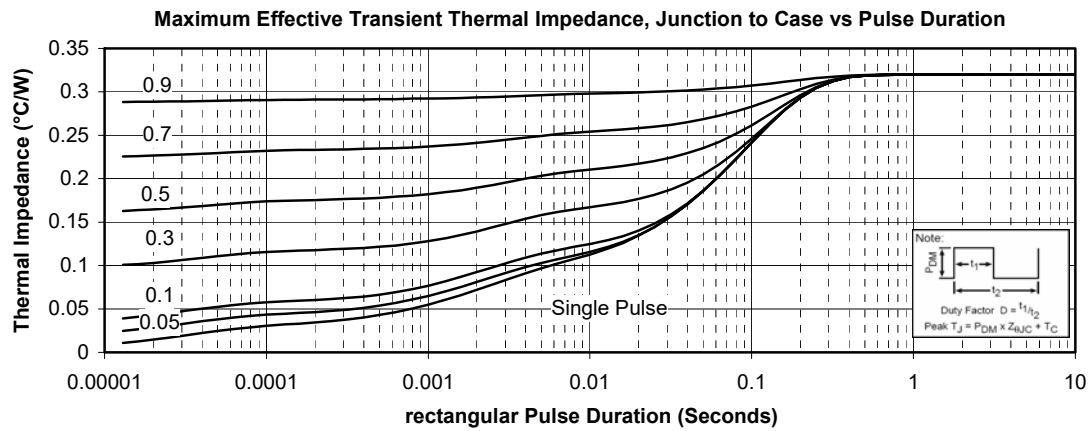
$$R_T = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]}$$

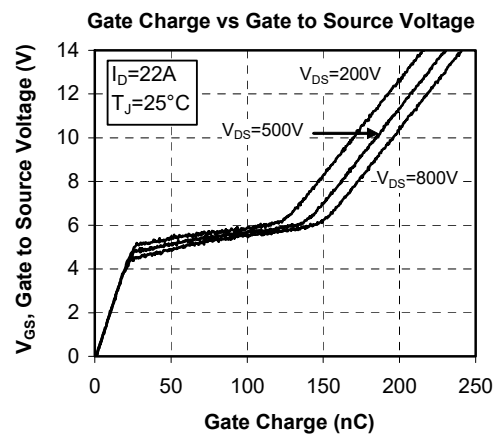
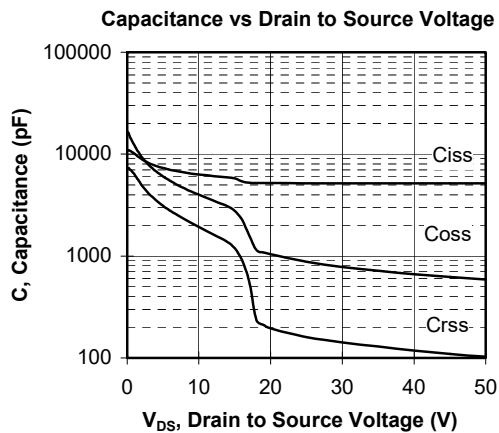
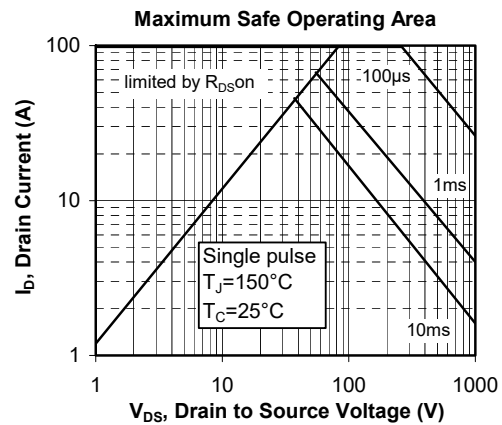
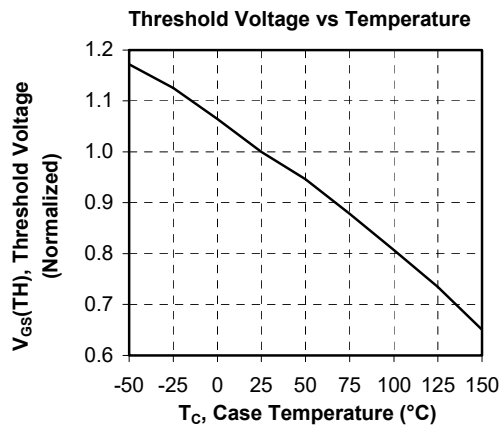
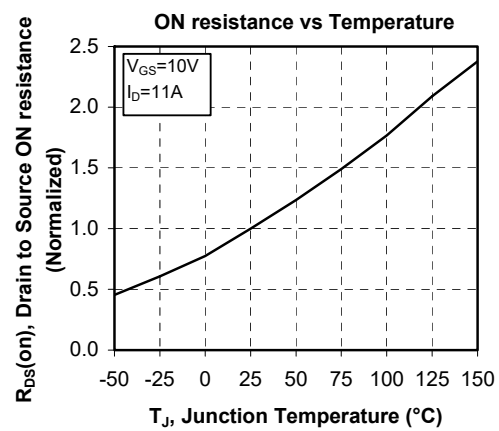
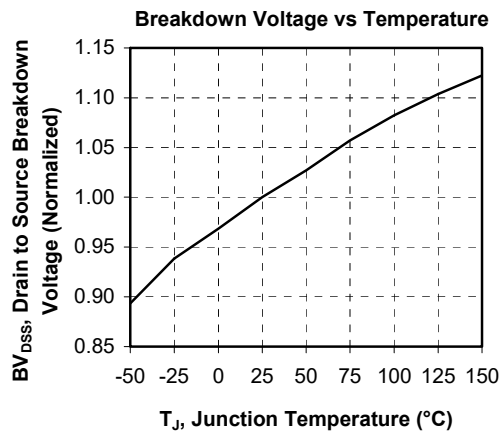
T: Thermistor temperature
 R_T: Thermistor value at T

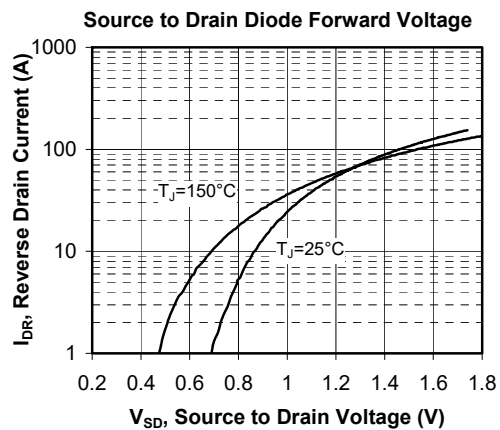
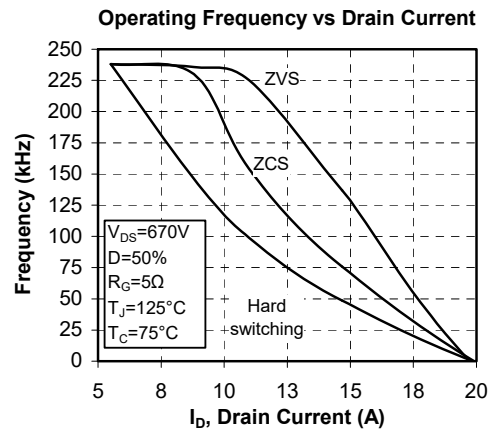
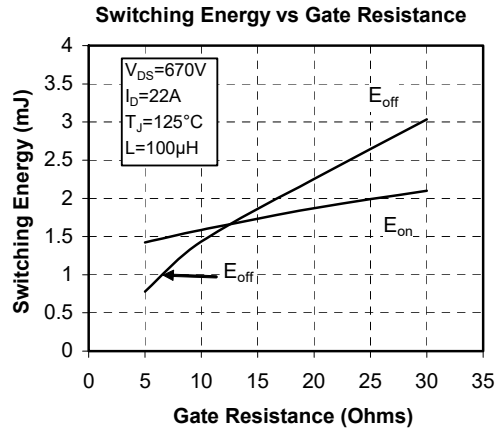
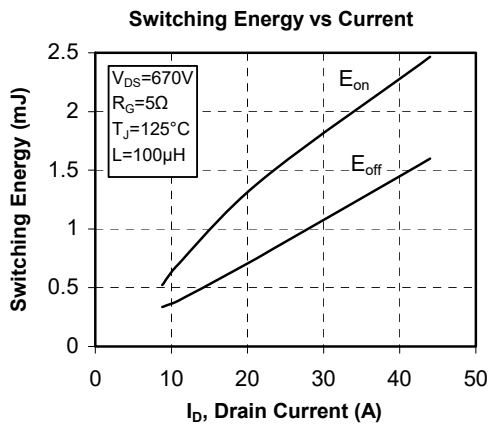
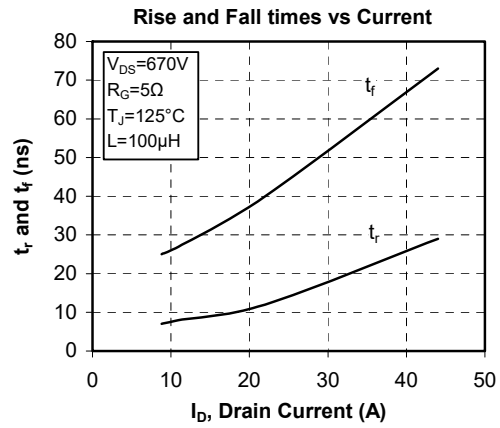
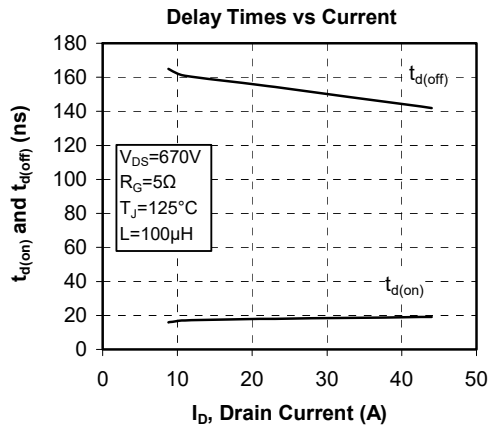
Package outline (dimensions in mm)


See application note 1906 - Mounting Instructions for SP3F Power Modules on www.microsemi.com

Typical Performance Curve







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